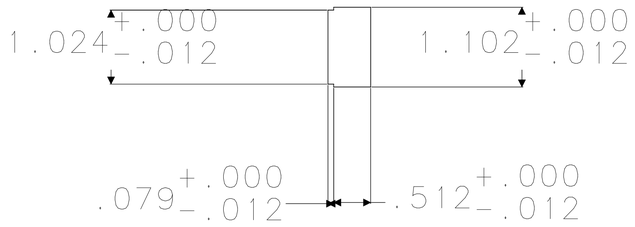
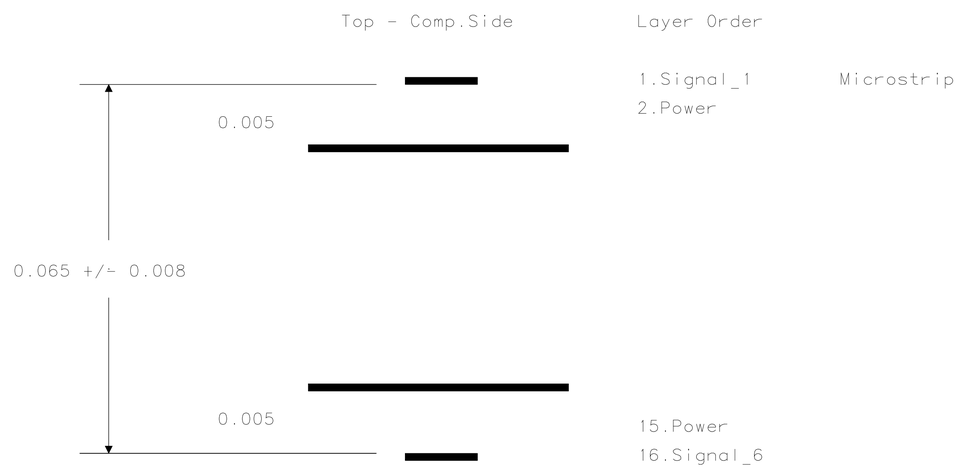
DWG.NO. 2851 SH REV. A





Board Characteristics

0. All dimensions are given in inches unless specified otherwise.
1. Material FR4

3. Minimum trace width and clearence: 0.007
4. 1 oz copper for all power layers and for Signal_1,2 (Top and Bottom)

5. Immersion Gold over copper, with min. Ni: 2.5-5 um; Au: 0.05-0.2 um.
   Apply Solder Mask over bare copper.
6. Board Thickness: 0.063 +/- 0.008

8. Silkscreen on Component and Solder Sides.

10. FHS tolerances: +/- 0.003 unless specified otherwise.
11. Interlayer spacing as specified

BOARD's DRILL SCHEDULE

DRILL SYMBOL	DRILL SIZE	COUNT	PLATED	Tolerance	COMMENT
○	.02	7	YES	---	
⊞	.035	6	YES	---	

UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN INCHES
TOLERANCES ARE:
FRACTIONS DECIMALS ANGLES
.XX
.XXX
DO NOT SCALE DRAWING

TREATMENT

FINISH

SIMILAR TO | ACT. WT | CALC WT

CONTRACT NO.

APPROVALS	DATE
DRAWN M.Bogdan	6/22/15
CHECKED M.Bogdan	6/22/15
ISSUED	

UNIVERSITY OF CHICAGO
ELECTRONICS DEVELOPMENT GROUP

TITLE
PMT PreAmp
Specification Drawing

SIZE B | FSCM NO. | DWG.NO. 2851 | REV. A

SCALE 1/2 | SHEET

THIS SHEET IS COMPUTER GENERATED